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(71) Applicant: **MERCK PATENT GMBH** [DE/DE]; Frank-
furter Strasse 250, 64293 Darmstadt (DE).

(72) Inventors: **HAYASHI, Masanobu**; c/o Merck Electronics
Ltd., 3330, Chihama, Kakegawa-shi, Shizuoka, 437-1412
(JP). **AOKI, Hiroyuki**; c/o Merck Electronics Ltd., 3330,
Chihama, Kakegawa-shi, Shizuoka, 437-1412 (JP).

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(54) Title: METHOD FOR MANUFACTURING PROCESSED SUBSTRATE

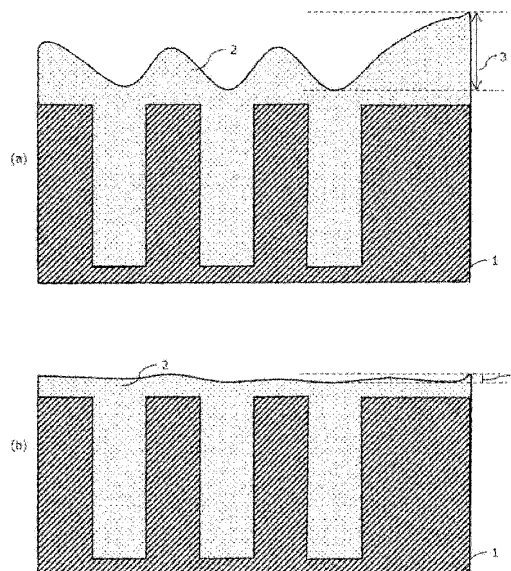


Figure 1

(57) Abstract: [Problem] To provide a method for manufacturing
a processed substrate with improved flatness. [Means for Solution]
A method for manufacturing a processed substrate comprising the
following steps: (a) applying a cured film forming composition on
a substrate having grooves in an amount sufficient to fill grooves
to form a composition layer; (b) removing the surplus part from
the composition layer by scraping off using a separation member
to form a substrate surface with improved flatness; and (c) heating
the substrate to cure the composition layer in which the surplus
part is removed.



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